



# 低價高導電金屬網格觸控模組

## Low Cost And High Conductivity Metal Mesh and Touch Panel Module

### 簡介 Introduction

工研院材化所整合運用金屬增厚材料技術配合簡易濕式製程技術達到金屬網格之製作技術，並有效運用於觸控模組之開發，達到低價化金屬網格製程與材料技術，並運用內埋金屬導線技術，達到高可撓及超薄化軟性可撓觸控應用。

Focused on wet chemistry metal thickening technique for fine line metal mesh application, an integrated technology was developed by MCL/ITRI. Combining with embedded conductor substrate technology applied in ultra-thin touch panel module, which has been successfully accomplished with only 110  $\mu\text{m}$  thickness and high flexibility.

### 特色 Features

濕法低價化金屬增厚技術，提升金屬網格線路電傳導特性並適合應用於大面積濕式塗佈製程應用。製程簡易，可適用於各種不同結構應用之觸控用透明導電膜。結合內埋金屬導線技術，實現超薄可撓式觸控模組應用需求。

A low cost wet process metal thickening technology improves the conductivity of metal mesh for large area coating process, which can be easily integrated in difference TP structure for TCO application. Combining with embedded conductor technology, a high flexible and thinner TP module is expected easily realized.

### 規格 Specifications

- Fine Line width : 3 $\mu\text{m}$
- Material : Silver
- Resistivity : 8 $\mu\Omega\text{cm}$
- TP : GG DITO, FF, G2(on-cell)

